

FMV12N50ES

FUJI POWER MOSFET

Super FAP-E^{3S} series

N-CHANNEL SILICON POWER MOSFET

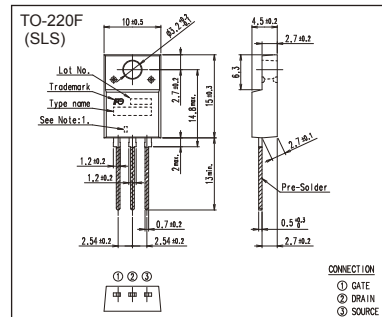
■ Features

- Maintains both low power loss and low noise
- Lower R_{DS(on)} characteristic
- More controllable switching dv/dt by gate resistance
- Smaller V_{GS} ringing waveform during switching
- Narrow band of the gate threshold voltage (3.7±0.5V)
- High avalanche durability

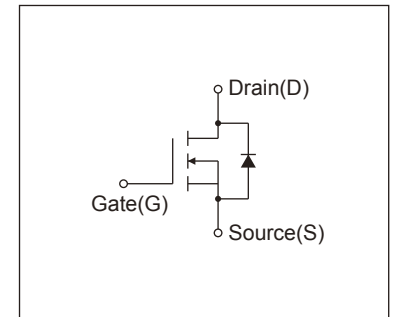
■ Applications

- Switching regulators
- UPS (Uninterruptible Power Supply)
- DC-DC converters

■ Outline Drawings [mm]



■ Equivalent circuit schematic



■ Maximum Ratings and Characteristics

● Absolute Maximum Ratings at T_c=25°C (unless otherwise specified)

Description	Symbol	Characteristics	Unit	Remarks
Drain-Source Voltage	V _{DS}	500	V	
	V _{DSSX}	500	V	V _{GS} = -30V
Continuous Drain Current	I _D	±12	A	
Pulsed Drain Current	I _{DP}	±48	A	
Gate-Source Voltage	V _{GS}	±30	V	
Repetitive and Non-Repetitive Maximum Avalanche Current	I _{AR}	12	A	Note*1
Non-Repetitive Maximum Avalanche Energy	E _{AS}	460.8	mJ	Note*2
Repetitive Maximum Avalanche Energy	E _{AR}	6.5	mJ	Note*3
Peak Diode Recovery dv/dt	dv/dt	6.3	kV/μs	Note*4
Peak Diode Recovery -di/dt	-di/dt	100	A/μs	Note*5
Maximum Power Dissipation	P _D	2.16	W	T _a =25°C
		65		T _c =25°C
Operating and Storage Temperature range	T _{ch}	150	°C	
	T _{stg}	-55 to + 150	°C	
Isolation Voltage	V _{ISO}	2	kVrms	t = 60sec, f = 60Hz

● Electrical Characteristics at T_c=25°C (unless otherwise specified)

Description	Symbol	Conditions	min.	typ.	max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	I _D =250μA, V _{GS} =0V	500	-	-	V
Gate Threshold Voltage	V _{GS} (th)	I _D =250μA, V _{DS} =V _{GS}	3.2	3.7	4.2	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =500V, V _{GS} =0V	-	-	25	μA
		V _{DS} =400V, V _{GS} =0V	-	-	250	
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±30V, V _{DS} =0V	-	10	100	nA
Drain-Source On-State Resistance	R _{DS} (on)	I _D =6A, V _{GS} =10V	-	0.427	0.50	Ω
Forward Transconductance	g _{fs}	I _D =6A, V _{DS} =25V	4.5	9	-	S
Input Capacitance	C _{iss}	V _{DS} =25V	-	1400	2100	pF
Output Capacitance	C _{oss}	V _{GS} =0V	-	160	240	
Reverse Transfer Capacitance	C _{rss}	f=1MHz	-	11.5	17.5	
Turn-On Time	td(on)	V _{cc} =300V	-	31	46.5	ns
	tr	V _{GS} =10V	-	18	27	
Turn-Off Time	td(off)	I _D =6A	-	83	124.5	
	tf	R _G =15Ω	-	16	27	
Total Gate Charge	Q _G	V _{cc} =250V	-	43	56	nC
Gate-Source Charge	Q _{GS}	I _D =12A	-	13	23	
Gate-Drain Charge	Q _{GD}	V _{GS} =10V	-	14	21	
Gate-Drain Crossover Charge	Q _{SW}		-	6	10	
Avalanche Capability	I _{AV}	L=2.44mH, T _{ch} =25°C	12	-	-	A
Diode Forward On-Voltage	V _{SD}	I _F =12A, V _{GS} =0V, T _{ch} =25°C	-	0.86	1.30	V
Reverse Recovery Time	t _{rr}	I _F =12A, V _{GS} =0V	-	0.37	-	μs
Reverse Recovery Charge	Q _{rr}	-di/dt=100A/μs, T _{ch} =25°C	-	5.0	-	μC

● Thermal Characteristics

Description	Symbol	Test Conditions	min.	typ.	max.	Unit
Thermal resistance	R _{th} (ch-c)	Channel to Case			1.920	°C/W
	R _{th} (ch-a)	Channel to Ambient			58.0	°C/W

Note *1 : T_{ch}≤150°C.

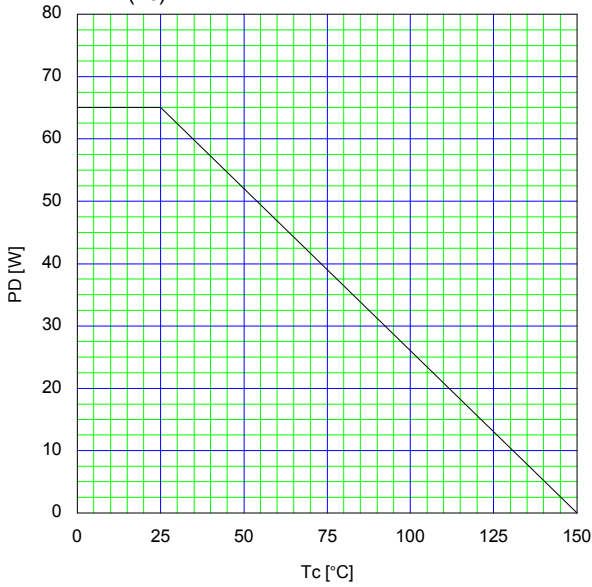
Note *2 : Stating T_{ch}=25°C, I_{AS}=5A, L=33.8mH, V_{cc}=60V, R_G=50Ω.
E_{AS} limited by maximum channel temperature and avalanche current.
See to 'Avalanche Energy' graph.

Note *3 : Repetitive rating : Pulse width limited by maximum channel temperature.
See to the 'Transient Thermal impedance' graph.

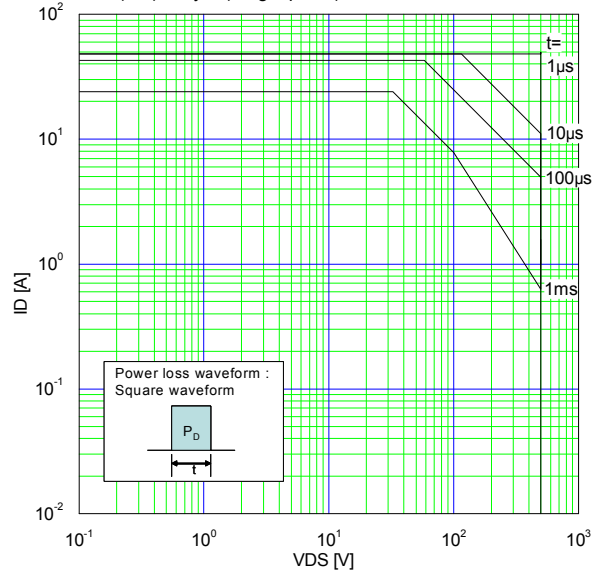
Note *4 : I_F≤I_D, -di/dt=100A/μs, V_{cc}≤BV_{DSS}, T_{ch}≤150°C.

Note *5 : I_F≤I_D, dv/dt=6.3kV/μs, V_{cc}≤BV_{DSS}, T_{ch}≤150°C.

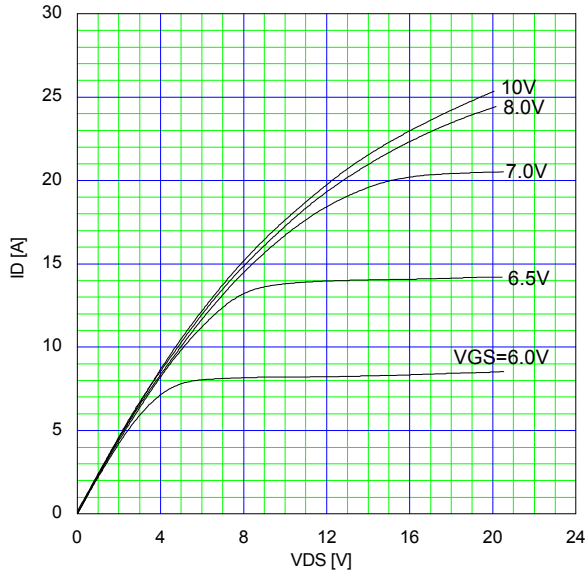
Allowable Power Dissipation
 $P_D = f(T_c)$



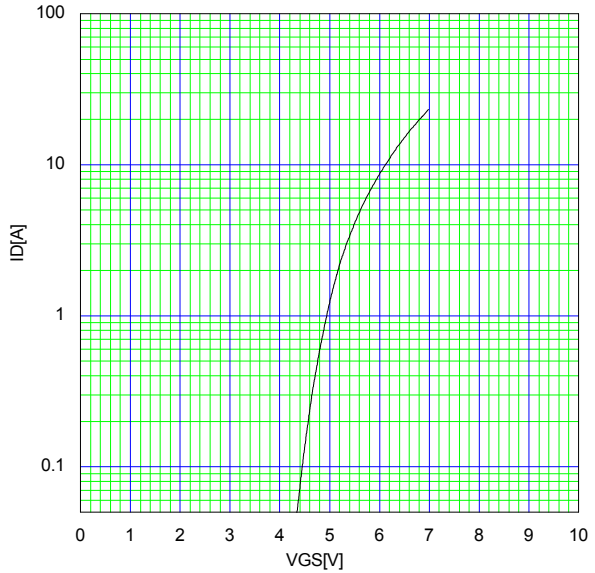
Safe Operating Area
 $I_D = f(V_{DS})$; Duty=0 (Single pulse), $T_c = 25^\circ\text{C}$



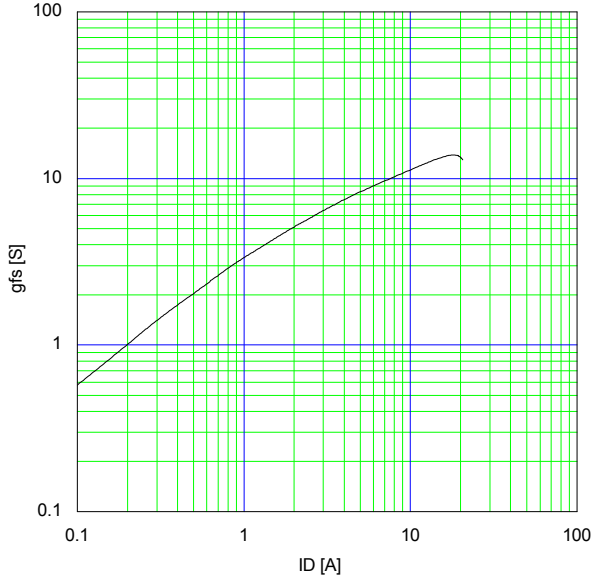
Typical Output Characteristics
 $I_D = f(V_{DS})$; 80 μs pulse test, $T_{ch} = 25^\circ\text{C}$



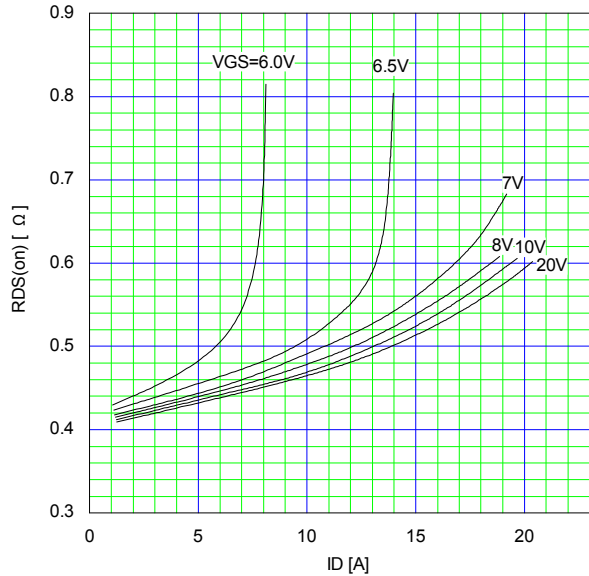
Typical Transfer Characteristic
 $I_D = f(V_{GS})$; 80 μs pulse test, $V_{DS} = 25\text{V}$, $T_{ch} = 25^\circ\text{C}$

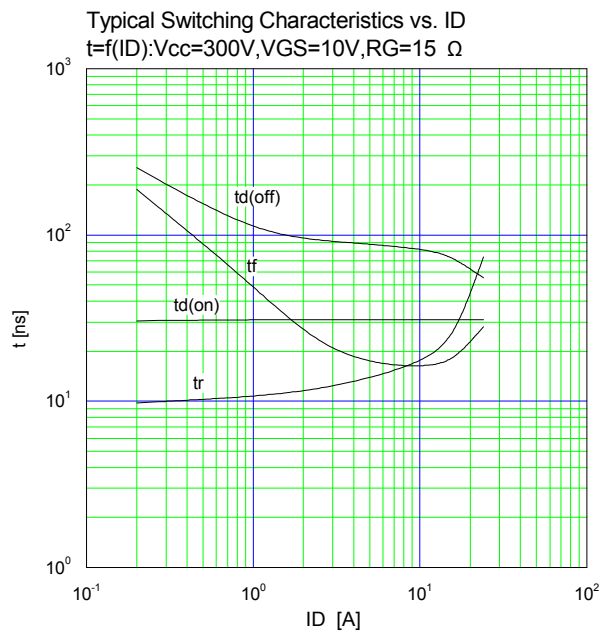
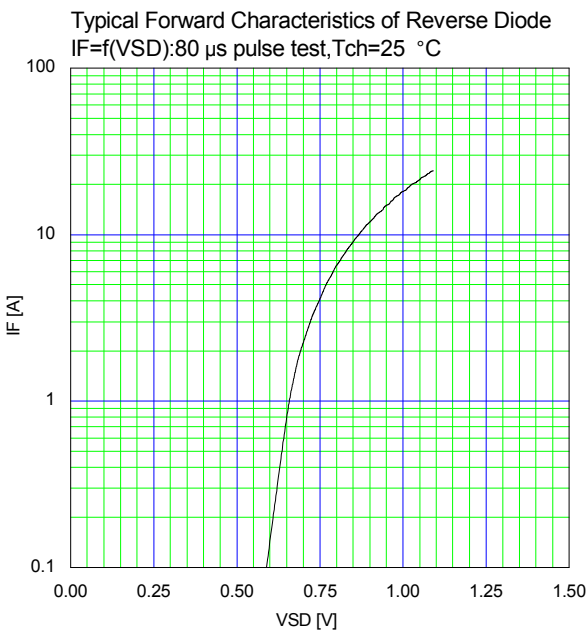
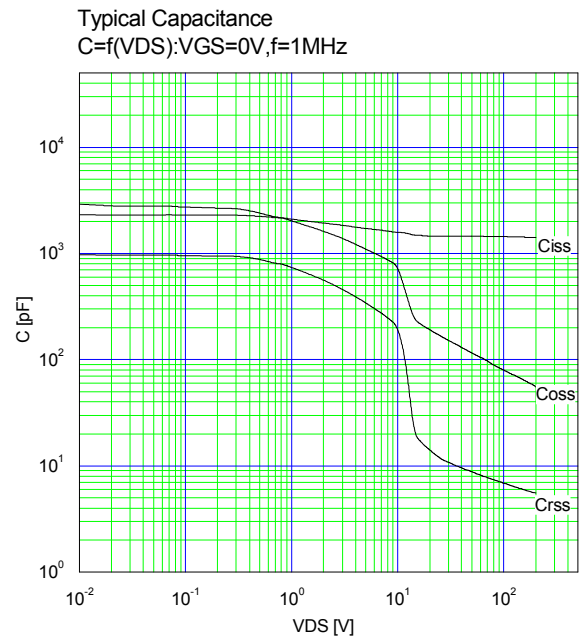
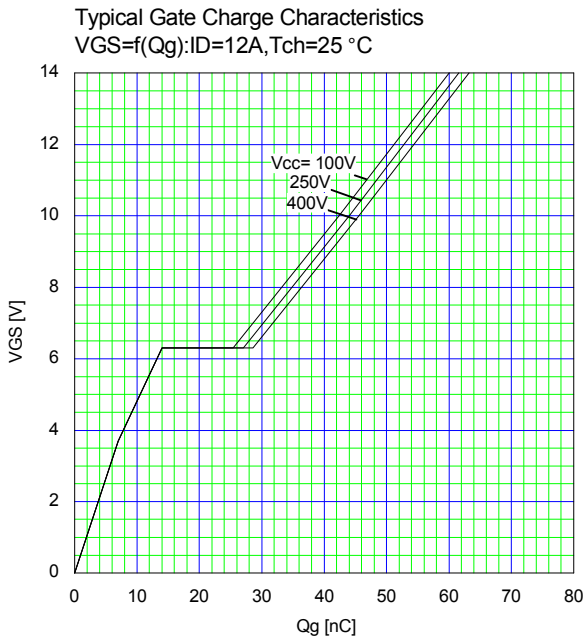
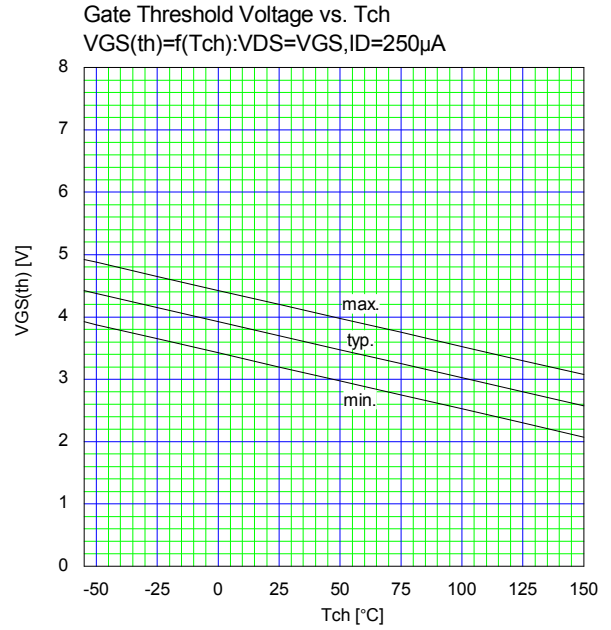
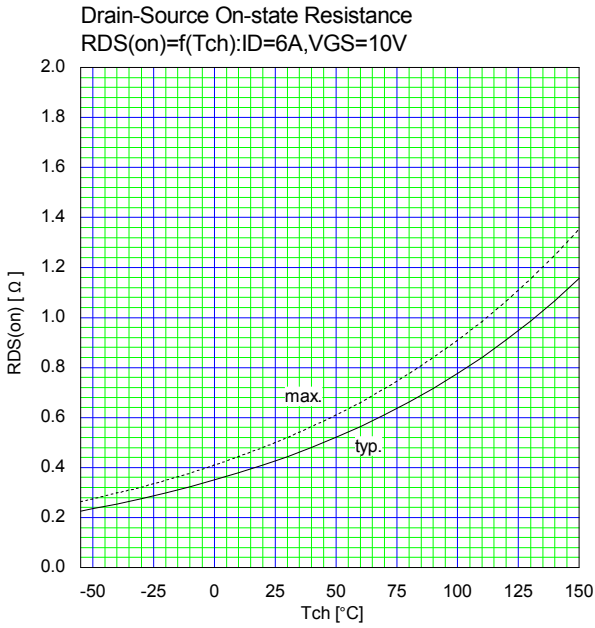


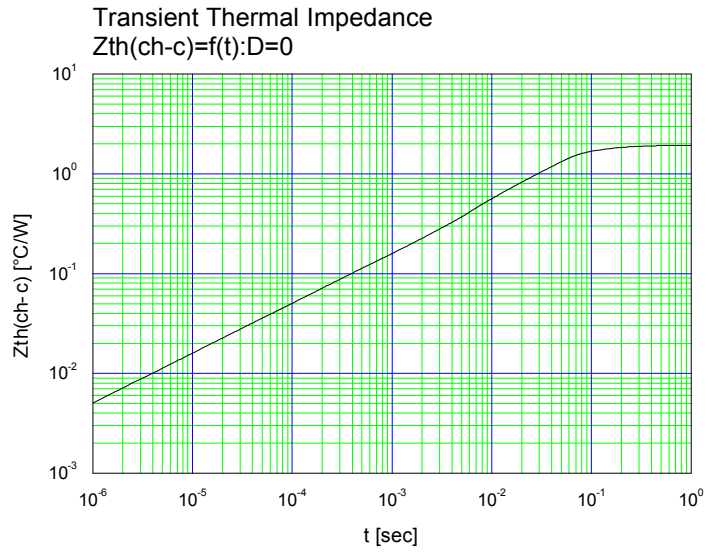
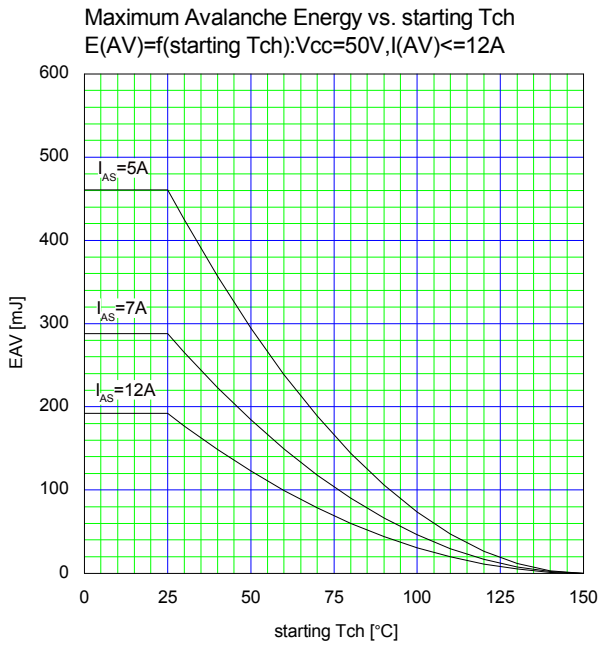
Typical Transconductance
 $g_{fs} = f(I_D)$; 80 μs pulse test, $V_{DS} = 25\text{V}$, $T_{ch} = 25^\circ\text{C}$



Typical Drain-Source on-state Resistance
 $R_{DS(on)} = f(I_D)$; 80 μs pulse test, $T_{ch} = 25^\circ\text{C}$







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